2SA1208

Rev.E Mar.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

TO-92LM PNP Silicon PNP transistor in a TO-92LM Plastic Package.

/ Features

h_{FE} C_{ob} 2SC2910

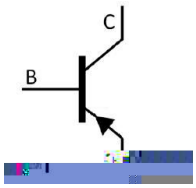
High breakdown voltage, Excellent linearity of h_{FE} and small C_{ob}, Fast switching speed complementary pair with 2SC2910.

/ Applications

80W

High voltage switching, Audio 80W output pre-driver applications.

/ Equivalent Circuit



/ Pinning

PIN1 Base PIN 2 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	R	S	T
h_{FE} Range	100~200	140~280	200~400

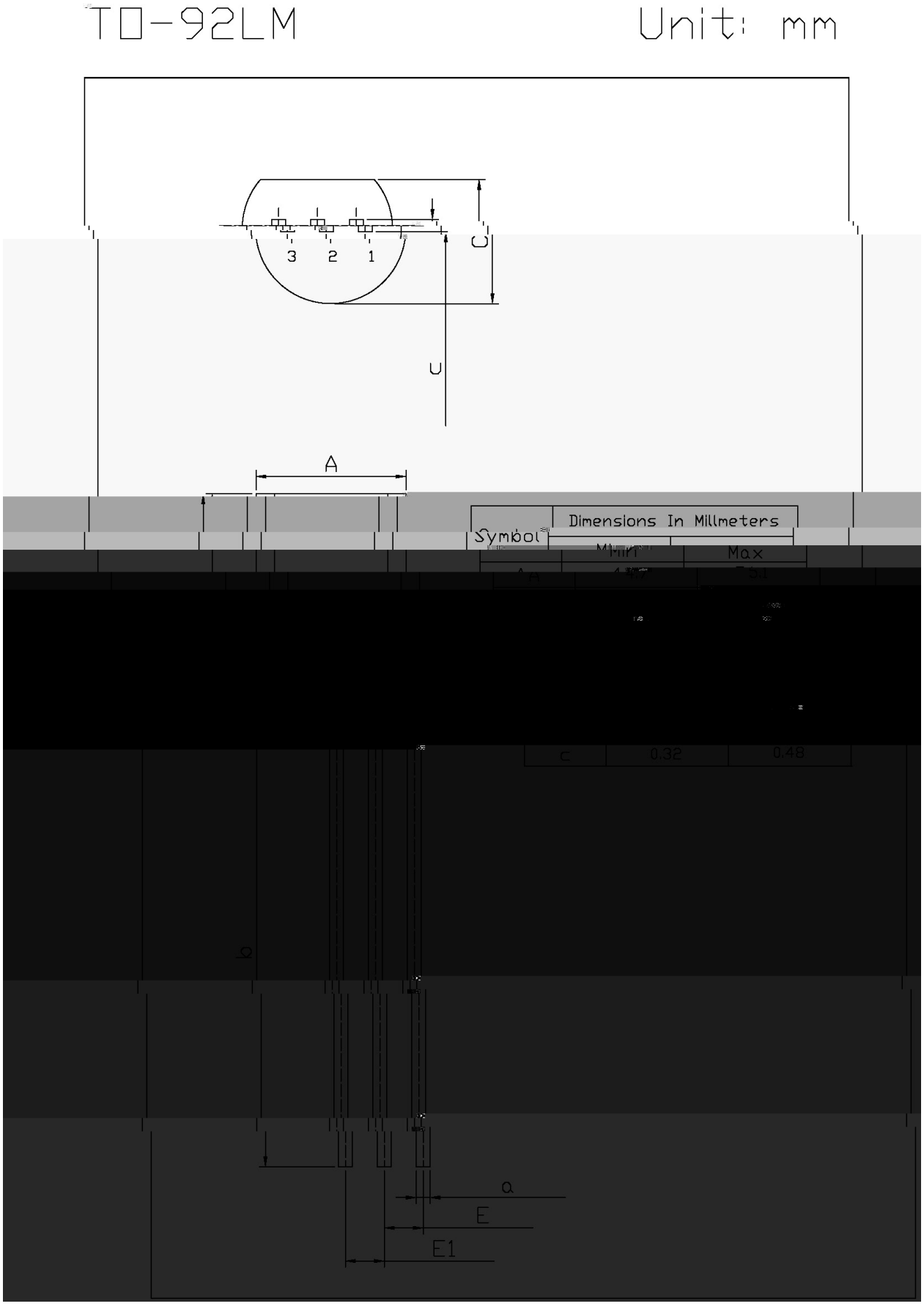
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-180	V
Collector to Emitter Voltage	V_{CEO}	-160	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-70	mA
Collector Current – Continuous(Pulse)	I_{CP}	-140	mA
Collector Power Dissipation	P_C	900	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

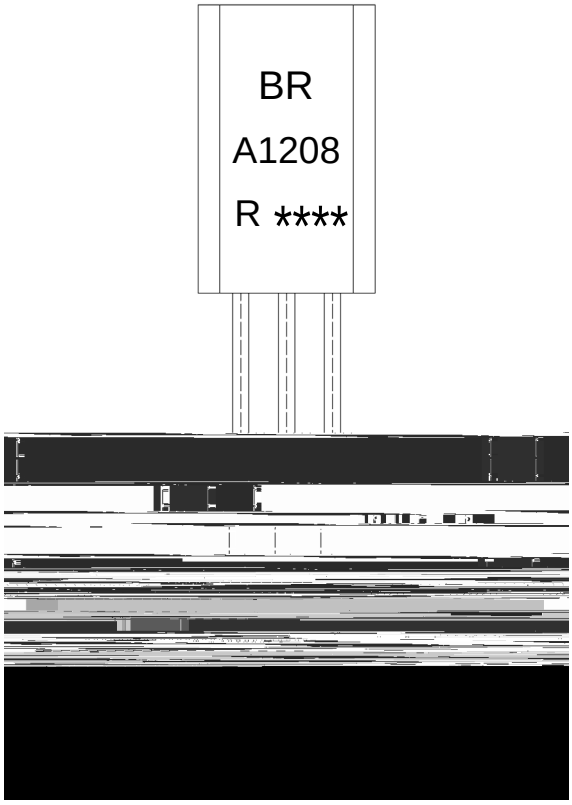
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	V_{CB}=-80V I_E=0			-0.1	μA
Emitter Cut-Off Current	I_{EBO}	V_{CB}=-4V I_C=0			-0.1	μA
DC Current Gain	h_{FE}	V_{CE}=-5V I_C=-10mA	100		400	
Transition Frequency	f_T	V_{CE}=-10V I_C=-10mA		150		MHz
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=-30mA I_B=-3.0mA		-0.14	-0.4	V
Collector output capacitance	C_{ob}	V_{CB}=-10V f=1.0MHz		2.5		pF
Turn-On Time	t_{on}	I_C=-10I_{B1}=10I_{B2}=-10mA		0.1		μs
Fall Time	t_f	I_C=-10I_{B1}=10I_{B2}=-10mA		0.2		μs
Storage Time	t_{stg}	I_C=-10I_{B1}=10I_{B2}=-10mA		1.0		μs

/ Electrical Characteristic Curve

/ Package Dimensions



/ Marking Instructions



BR:

A1208

R: h_{FE}

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Note:

BR:	Company Code.
A1208:	Product Type.
R:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)

	Note:
1 25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2 255±5 5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Tf0.56D935.8(5(.7150)]TJ/TT7 1 Tf314.9486 0